



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Product Summary

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$ $T_A = +25^\circ C$
450V	50Ω @ $V_{GS} = 10V$	140mA

## Description and Applications

This MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

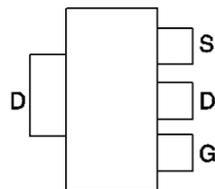
## Mechanical Data

- Package: SOT223
- Package Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 
- Weight: 0.112 grams (Approximate)

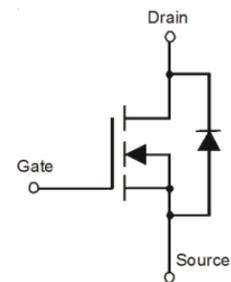
SOT223 (Type DN)



Top View



Pinout - Top View



Equivalent Circuit

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	450	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current V <sub>GS</sub> = 10V	I <sub>D</sub>	140	mA
Pulsed Drain Current	I <sub>DM</sub>	600	mA

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation	P <sub>D</sub>	2	W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

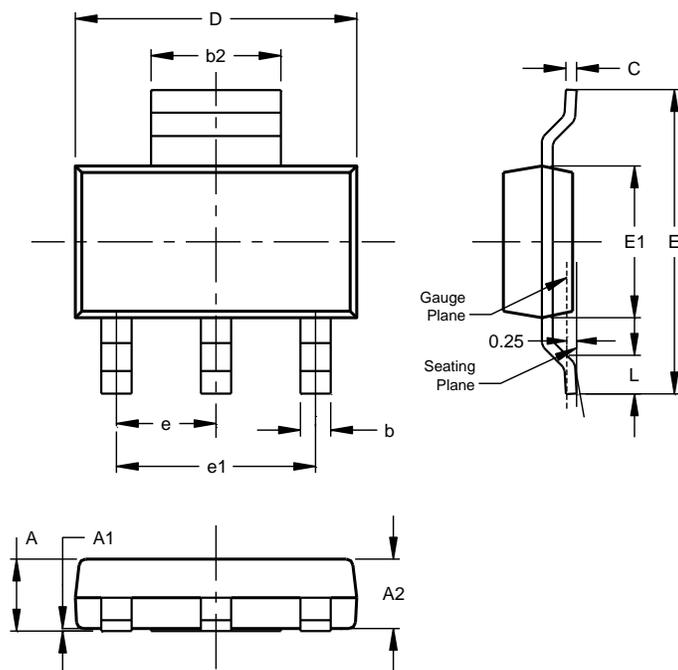
**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	450	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	10	μA	V <sub>DS</sub> = 450V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±20	nA	V <sub>DS</sub> = 405V, V <sub>GS</sub> = 0V, T = +125°C (Note 6)
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±20	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	—	3	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1mA
Static Drain-Source On-State Resistance (Note 5)	R <sub>DS(ON)</sub>	—	—	50	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 100mA
On-State Drain Current (Note 5)	I <sub>D(ON)</sub>	150	—	—	mA	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 10V
Forward Transconductance (Notes 5 and 6)	g <sub>fs</sub>	100	—	—	mS	V <sub>DS</sub> = 25V, I <sub>D</sub> = 100mA
<b>DYNAMIC CHARACTERISTICS (Note 6)</b>						
Input Capacitance	C <sub>iss</sub>	—	—	70	pF	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	—	10	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	—	4	pF	
Turn-On Delay Time (Note 7)	t <sub>D(ON)</sub>	—	—	7	ns	V <sub>DD</sub> = 25V, I <sub>D</sub> = 100mA
Turn-On Rise Time (Note 7)	t <sub>R</sub>	—	—	7	ns	
Turn-Off Delay Time (Note 7)	t <sub>D(OFF)</sub>	—	—	16	ns	
Turn-Off Fall Time (Note 7)	t <sub>F</sub>	—	—	10	ns	

- Notes:
5. Measured under pulsed conditions. Width=300μs. Duty cycle ≤ 2%.
  6. Sample test.
  7. Switching times measured with 50Ω source impedance and <5ns rise time on a pulse generator.

## Package Outline Dimensions

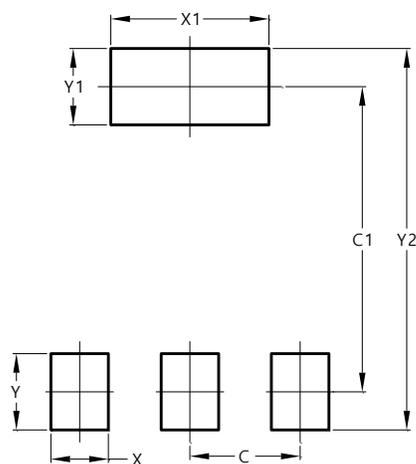
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Dim	Min	Max	Typ
A	--	1.70	--
A1	0.01	0.15	--
A2	1.50	1.68	1.60
b	0.60	0.80	0.70
b2	2.90	3.10	--
c	0.20	0.32	--
D	6.30	6.70	--
E	6.70	7.30	--
E1	3.30	3.70	--
e	--	--	2.30
e1	--	--	4.60
L	0.85	--	--
All Dimensions in mm			

## Suggested Pad Layout

SOT223 (Type DN)



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00